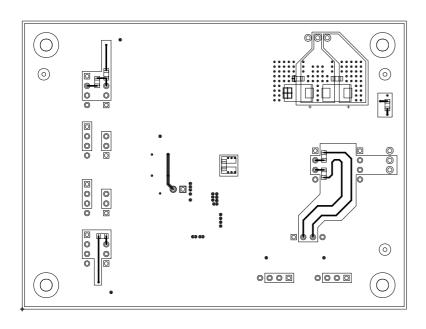
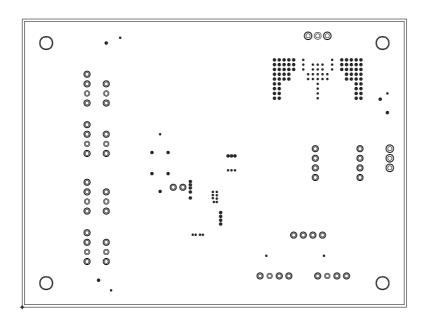


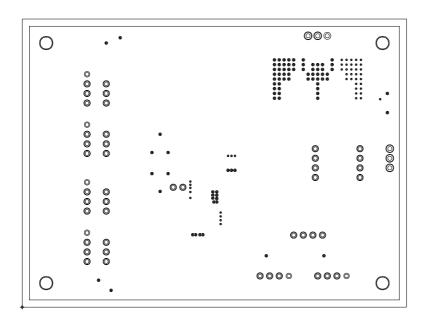
KTY PIONS	BOARD NAME: XXXXXXXX	BOARD REV:	KSID: 16940	JOB NUMBER: 129285
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: XLXAXXXDXX X.X XIXXXX XXXXXXXXXXXXXXXXXXXXXX		



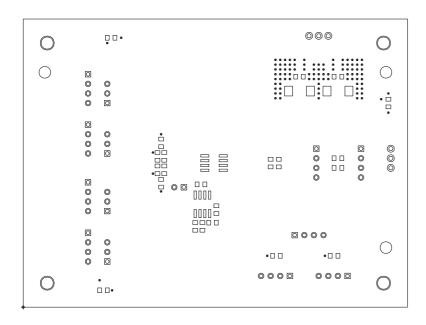
KTY PION Solutions	BOARD NAME: XXXXXXXX	BOARD REV:	KSID: 16940	JOB NUMBER: 129285
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: XLANAYADRX X4X X-X XBXXXIXIXXMX XXIDE		



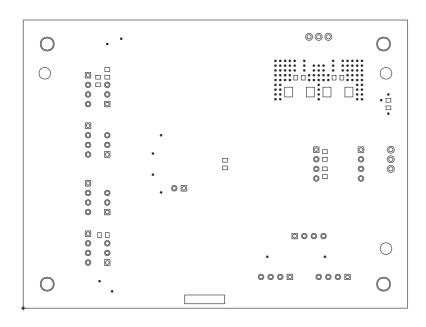
Kry pions	BOARD NAME: XXXXXXXX	BOARD REV:	KSID: 16940	JOB NUMBER: 129285
		FROM TOP LAYER DESCRIPTION: XLANNODRX YZX X-X XGNNOX YPXLYANNE		



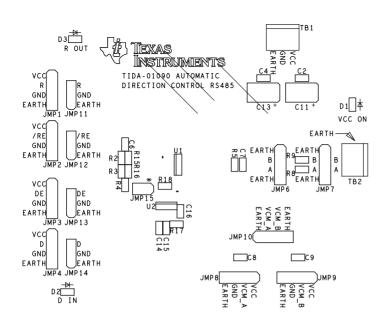
KTY PIONS	BOARD NAME: XXXXXXXX	BOARD REV:	KSID: 16940	JOB NUMBER: 129285
		FROM TOP LAYER DESCRIPTION:  X.XAXXXEXTX X3X X-X XPXWXX XPX.XAXXVE		



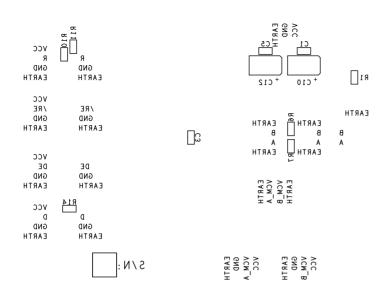
KTY PION SOLUTIONS	BOARD NAME: XXXXXXXX	BOARD REV:	KSID: 16940	JOB NUMBER: 129285
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION:  XXXXIXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX		



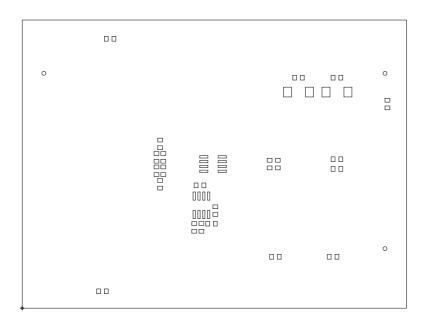
KTY PIONS	BOARD NAME: XXXXXXXX	BOARD REV:	KSID: 16940	JOB NUMBER: 129285
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: XSXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX		



MY PION SOLUTIONS	BOARD NAME: XXXXXXXX	BOARD REV:	KSID: 16940	JOB NUMBER: 129285
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPT  XSXIXLXXXXXXXX	TION: NEXEMIX XTXXXPX X X X X	



KTY PION Solutions	BOARD NAME: XXXXXXXX	BOARD REV:	KSID: 16940	JOB NUMBER: 129285
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPT  XSXIXLXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	TON: EXENNX XBXXXTXTXXXXXX X	



Krypton solutions	BOARD NAME: XXXXXXXX	BOARD REV:	KSID: 16940	JOB NUMBER: 129285
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION:  VPANSXIDEMANSXXX XIXXPX X X X X X		

0			0
	0.0		0

KTY PIONS	BOARD NAME: XXXXXXXX	BOARD REV:	KSID: 16940	JOB NUMBER: 129285
	ALL ARTWORK LAYERS VIEWED FROM TOP	TOP LAYER DESCRIPTION:  VPANSXIVEMANSKX XSXXIXIXXXXXX X X		

ART FILM - ASSY\_TOP

8	7	6	5	4	3	2	1
B  B							В
A 8		6	5	4	DRAWN:L RELEASE	BOARD NAME :  ASSEMBLY DRAW	ENGINEER H TEJAS  XXXXXXXXXXXX  ING (TOP SIDE)  JOB NO. 129285  A  SHEET 1 OF 2  1

ART FILM - ASSY\_BOT

	8	7	6	5	4	3	2	1
D								
C								
В								B
A	8	7	6	5	4	RELEASED:	BOARD NAME :  ASSEMBLY DRAW	ENGINEER  1ENTS H TEJAS  XXXXXXXXXXXXX  ING (BOTTOM SIDE)  JOB NO. REV.  129285 A  SHEET 2 OF 2

ART FILM - FABRICATION

	8 7	6	5	4	3	2 1			
		TABLE 1:				DESIGN INFORMATION			
		LAYER	LAYER DIFFIRENTIAL PAIR DIFF TRACE		NGLE ENDED REFERENCE	BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)			
		NO.		SPACING IMPEDANCE (OHMS) TR	ACE WIDTH LAYER	NUMBER OF LAYERS: 4 MIN. TRACK WIDTH: 15.0 MIL			
		LAYER 1	TOP	50 +/- 10%	.017" LAYER 2	MIN. CLEARANCE : <u>X.X MIL</u> MIN. VIA PAD/DRILL: <u>20/10 MIL</u>			
	* AIR O MIL  * SOLDERMASK-0.8MIL 0.8 MIL L1: COPPER_1/20Z_PLATED 1.4 MIL	LAYER 2				MIN. ANNULAR RING 2 MIL EXTERNAL PER IPC-6012C CLASS 2			
D		LAYER 3		50 . / 10%	017"	REGISTRATION TOLERANCES: METAL +/- X MIL, HOLES +/- X MIL			
	* FILL_0.250 9.84 MIL	LAYER 4	ВОТТОМ	50 +/- 10% 0	0.017" LAYER 3	IMPEDANCE CONTROL: NONE X YES - SEE TABLE 1			
	L2: COPPER_1.00Z 1.4 MIL					MIXED DIELECTRIC: X NO YES  LAMINATE MATERIAL:			
						X FR-4 HIGH Tg ROGERS 4350B OTHER:			
		SPECIA	AL FAB NOTES:			THICKNESS:			
	* CORE_1.00 35.12 MIL	1 : F A 2 :	B SHOP MUST FOLLOW THE SOLDER MASK REVIEW L	AYERS.	X 0.062" +/-10% 0.093" +/-10% OTHER:				
					TOLERANCE:  BOW & TWIST:  X IPC-6012C TYPE 3 CLASS 2 X IPC-6012C TYPE 3 CLASS 2	_			
						OTHER +/-			
						COPPER THICKNESS (FINISHED):			
	L3: COPPER_1.00Z 1.4 MIL					OUTER: 1/4 OZ. 1/2 OZ. X 1.0 OZ. 2.0 OZ.			
	* FILL_0.250 9.84 MIL	PLACE	DRILL CHART HERE:			INNER SIGNAL: 1/4 OZ. 1/2 OZ. 1.0 OZ. 2.0 OZ.			
	L4: COPPER_1/20Z_PLATED 1.4 MIL  * SOLDERMASK-0.8MIL 0.8 MIL  * AIR 0 MIL					INNER PLANE: 1/4 OZ. 1/2 OZ. X 1.0 OZ. 2.0 OZ.			
	DESIGN CROSS SECTION CHART TOTAL THICKNESS 62 MIL					OTHER:			
						BOARD FINISH: SILKSCREEN: X TOP X BOTTOM			
						SILKSCREEN COLOR: X WHITE OTHER			
						SOLDERMASK: (PER IPC-6011,6012)			
						X TOP X BOTTOM			
						SOLDERMASK COLOR: X GREEN BLUE OTHER			
						THROUGH-HOLE VIA TREATMENT:			
						OPEN X TENTED IDENTIFIER: ALL x MIL VIAS			
						VIA FILL USING NON-CONDUCTIVE EPOXY:			
						X NO YES IDENTIFIER: ALL x MIL VIAS			
						THIEVING ALLOWED: YES X NO			
						BOARD SURFACE TREATMENT:			
						X NICKEL/GOLD (ENIG) ORGANIC (OSP) HASL ENEPIG	IPIG D		
В						IMMERSION TIN OTHER  FOR WIRE BONDING:			
	4.000					HARD GOLD SOFT GOLD PER SUPPLIED ARTWORK			
						ADDITIONAL REQUIREMENTS:			
		$\overline{\Phi}$				X MICRO-SECTION X TDR REPORTS/COUPONS X ELECTRICAL TEST			
						X CERTIFICATES OF COMPLIANCE X RoHS X UL 94V-0			
						VENDOR MARKING:			
	3.0					VENDOR DATE CODE, UL, LOGO: ETCH X SILKSCREEN BREAK-AWAY	/		
A CAD ORI						X IN AN OPEN AREA WHERE INDICATED (SEE DRAWING)			
		lacksquare				CUSTOMED	4		
					1717mfam	CUSTOMER ENGINEER  TEXAS INSTRUMENTS H TEJAS			
	ORIGIN				Solutions	BOARD NAME : xxxxxxxxxxxx			
						FABRICATION DRAWING	7		
	BOARD NAME: BOARD REV. KSID.	JOB NUMBER:			<u> </u>	APPROVALS DATE SIZE KSID NO. JOB NO. REV	<u> </u>		
	BOARD REV: KSID:  XXXXXXXXX  ALL ARTWORK LAYERS VIEWED FROM TOP  LAYER DESCRIPTION:  X7AXBARXIXXAXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX	JOB NUMBER: 129285				DRAWN:LYNN WITTER 04-12-16 RELEASED: xxx			
					-	DO NOT SCALE DRAWING SCALE NONE SHEET 1 OF 1	ال		
	<b>Q</b> 7	6	5	$\Lambda$	3	1			

ART FILM - FABRICATION

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